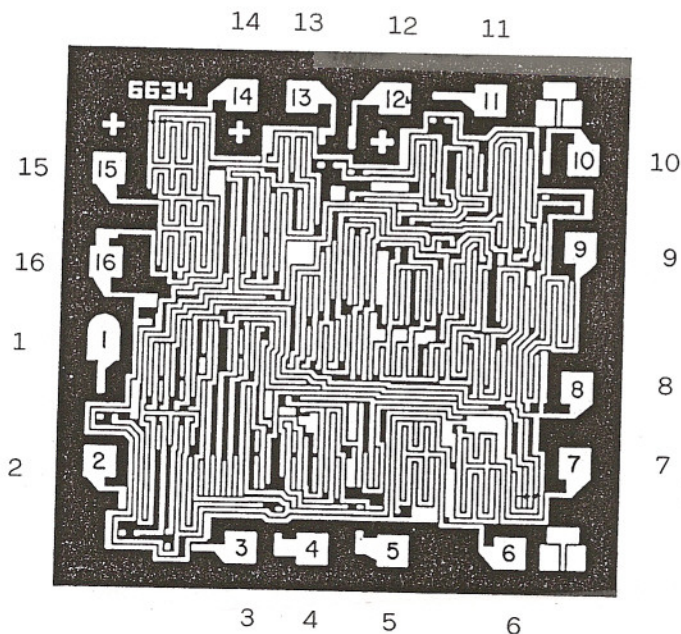




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>PAD NO</u>	<u>FUNCTIONS</u>
1	D4
2	D5
3	D6
4	D7
5	E _I
6	Q2
7	Q1
8	VSS
9	Q0
10	D0
11	D1
12	D2
13	D3
14	GS
15	E _O
16	VDD

Top Material:
Backside Material:
Bond Pad Size:
Backside Potential:
Mask Ref:

APPROVED BY:MG

DIE SIZE :76 x 73

DATE: 10/28/08

MFG:RCA

THICKNESS:

P/N:CD4532BH